

What is claimed is:

1. A method for producing a microtransponder comprising the  
5 following steps:

applying an antenna metallization having a first and a second connecting end to a support substrate;

10 applying a connecting metallization to a flexible support foil;

15 a) applying a circuit chip having a first and a second connecting area to said connecting metallization in such a way that at least the first connecting area of the circuit chip is connected to the connecting metallization in an electrically conductive manner;

20 b) joining the support substrate and the support foil in such a way that the connecting metallization is connected to the first connecting end of the antenna metallization in an electrically conductive manner, and that the second connecting area of the circuit chip is connected to the second connecting end of the antenna metallization in an electrically conductive manner; and

25 c) joining edge areas of the flexible support foil to neighbouring areas of the support substrate so as to encapsulate at least the circuit chip.

- 30 2. A method according to claim 1, wherein the edge areas of the flexible support foil are welded to the neighbouring areas of the support substrate.

3. A method according to claim 1, wherein the edge areas of the flexible support foil are joined to the neighbouring areas of the support substrate by means of an adhesive.

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4. A method according to claim 1, wherein in step b) a first and a second connecting metallization are applied [to the flexible support foil], and wherein in step c) the circuit chip, which is provided with said first and second connecting areas on a first main surface thereof, is applied to said first and said second connecting metallizations in such a way that the first connecting area is connected to the first connecting metallization in an electrically conductive manner and the second connecting area is connected to the second connecting metallization in an electrically conductive manner, the second connecting area being, in step d), connected via the second connecting metallization to the second connecting end of the antenna metallization in electrically conductive manner.

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15 5. A method according to claim 1, wherein the circuit chip applied in step c) has the first connecting area on a first main surface thereof and the second connecting area on a second main surface thereof, which is located opposite said first main surface.

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30 ⑥ 6. A method according to claim 4, wherein in step d) the support foil and the support substrate are joined in such a way that the antenna metallization and the circuit chip are arranged on the same main surface of the support substrate.

-  7. A method according to claim 4, wherein the circuit chip is introduced in step d) in an opening in the support-substrate main surface to which the antenna metallization has been applied.

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- 0 8. A method according to claim 6, wherein an insulator structure is provided so as to insulate the second connecting metallization from the antenna metallization with the exception of the location at the second connecting end of the antenna metallization.

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9. A method according to claim 4, wherein the support foil and the support substrate are joined in step d) in such a way that the antenna metallization and the circuit chip are arranged on opposed main surfaces of the support substrate, the first and second connecting metallizations being connected by means of through-contacts to the first and second connecting ends of the antenna metallization.

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- 20 10. A method according to claim 4, wherein in step d) the circuit chip is introduced in an opening provided in the main surface of the support substrate which is located opposite the main surface having the antenna metallization applied thereto, the first and second connecting metallizations being connected by means of through-contacts to the first and second connecting ends of the antenna metallization.

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11. A method according to claim 5, wherein the support foil  
30 and the support substrate are joined in step d) in such a  
way that the antenna metallization and the circuit chip  
are arranged on the same main surface of the support sub-  
strate.

12. A method according to claim 5, wherein in step d) the circuit chip is introduced into an opening provided in the main surface of the support substrate which is located opposite the main surface having the antenna metallization applied thereto, the connecting metallization being connected via a through-contact to the first connecting end of the antenna metallization.

13. A method according to claim 1, wherein step e) is executed in a vacuum or making use of a protective gas.